



NGAC TC907-09 is a thermally conductive and electrically insulating epoxy casting adhesive. It was formulated for staking and setting transistors, diodes, resistors, integrated circuits and other heat-sensitive components in printed circuit electronic applications. This medium viscosity material develops strong, durable and high-impact bonds which improve heat transfer while maintaining electrical insulation.

NGAC TC907-09 bonds readily to itself and to metals, silica, steatite, alumina sapphire and other ceramics, glass, plastics and many other materials, because its coefficient of thermal expansion provides a good match for those materials over a wide temperature range. It provides excellent resistance to salt solutions, mild acids, alkalis and many other chemicals including petroleum solvents, lubricating oils, and alcohol.

NGAC TC907-09 is a 100 % solids material that will cure at room temperature and has been used extensively in backfill applications for transceiver assembly where low moisture absorption and low shrinkage upon cure to maintain lens alignment are critical. This material passes NASA outgassing requirements.

Please email info@nextgenadhesives.com or call (978) 436-9600 for a FREE SAMPLE.